

ELECTROPLATING SYSTEM AND PRESSURE DEVICE THEREOF

ABSTRACT

An electroplating system for depositing a plating material on an object includes a pressure device and an anode element. The pressure device includes a lid having first and second through holes and a base having a chamber, conduction holes and third through holes located in the chamber. Each of the conduction tubes includes a conduction hole connecting to one of the third through holes. When the lid covers the chamber, the first through holes communicate with the chamber for spraying an electroplating solution toward the object and the second through holes reveal the conduction holes. A passage of electric force line is formed in the conduction holes and the third through holes filled with the electroplating solution, and the anode element is located outside the passage of electric force line. The electroplating system can prevent defective plating and enhance plating efficiency.

FIG. 3